

All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters. Unless otherwise specified, dimensions have a tolerance of ± 0.13 and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION

This specification covers the requirements for application of SFP and SFP+ surface mount PT connectors and cage assemblies to interconnect SFP and SFP+ fiber optic or copper transceiver modules to printed circuit (pc) boards. The connectors are available in 20, 30, 40, and 70 positions with contact spacing on 0.8 mm centerlines; however, **ONLY the 20-position connector is designed to be used with these cage assemblies.** The cage assemblies are available in single port or ganged 1x2, 1x4, or 1x6 configurations (two, four, or six adjoining ports), and with or without a light pipe. The light pipe is used to transmit light from an LED on the pc board to a panel (information for cage assemblies with light pipe is not included in this document). Each cage assembly is designed to be inserted into a bezel after being seated onto the pc board.

The connector is supplied in tape-and-reel form for manual or high-speed automatic machine placement (typically vacuum pick and place). The cage assemblies are supplied in plastic tray packaging for manual placement.

When corresponding with TE Connectivity (TE) Personnel, use the terminology provided in this specification to facilitate your inquiries for information. Basic terms and features of this product are provided in Figure 1.

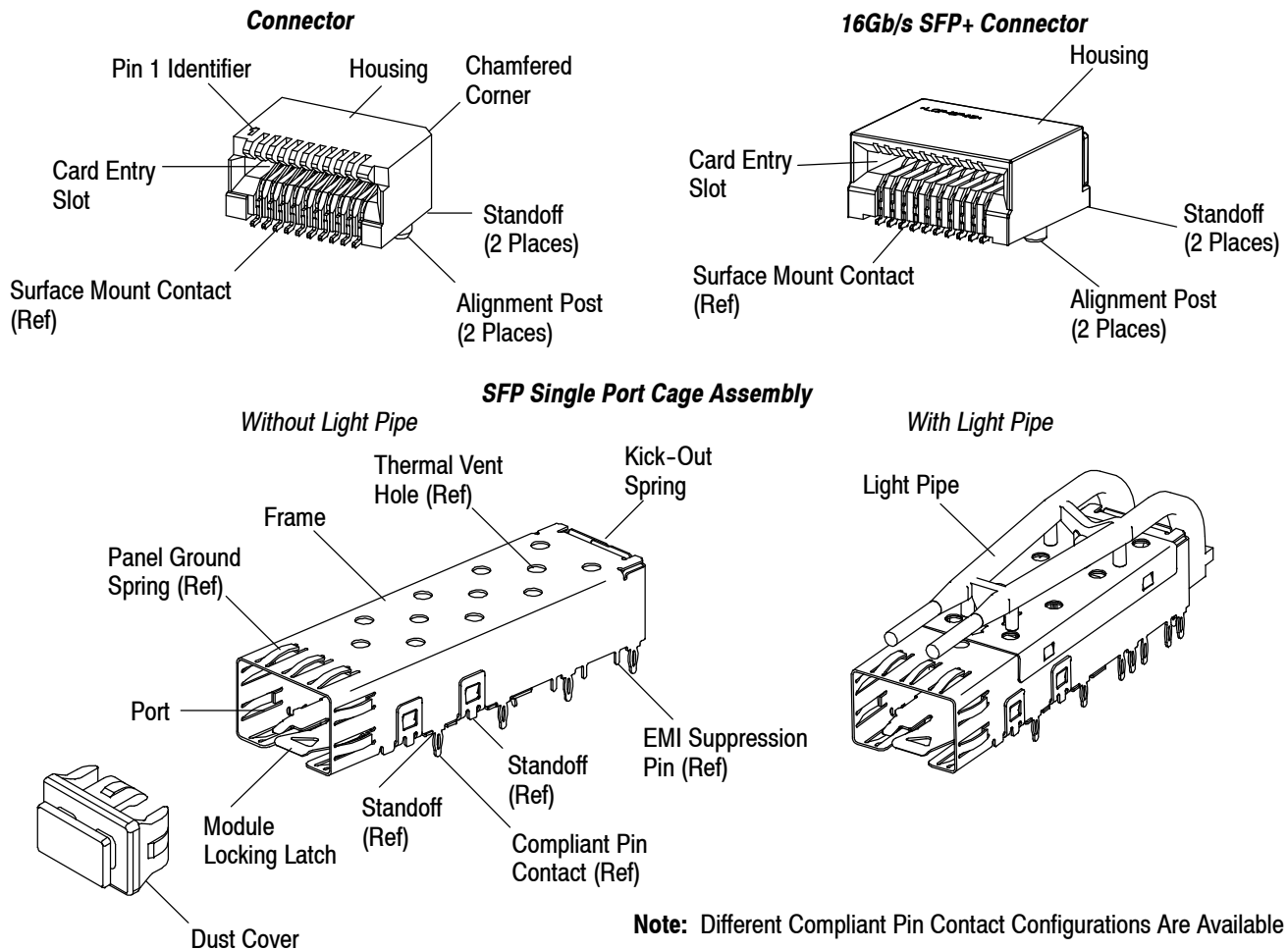
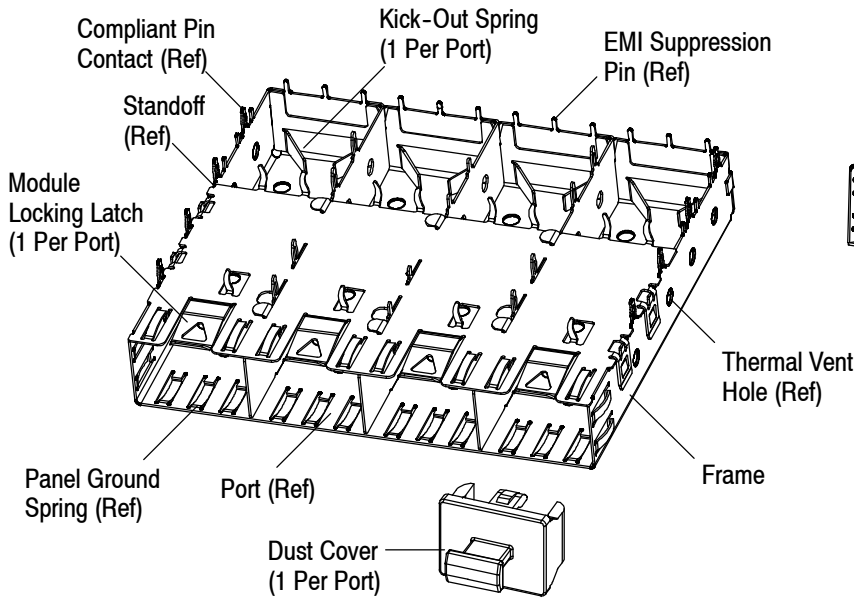


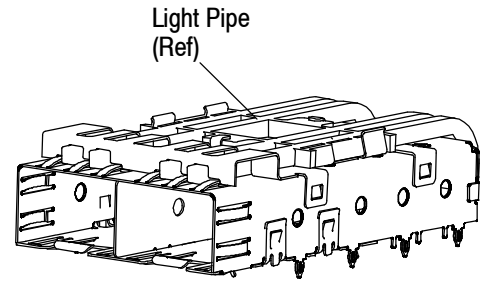
Figure 1 (Cont'd)

SFP Ganged Cage Assembly

1 × 4 Configuration Without Light Pipe (Shown With Bottom Side Up)

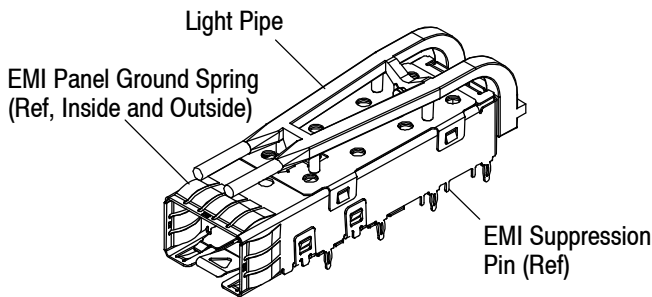


1 × 2 Configuration With Light Pipe



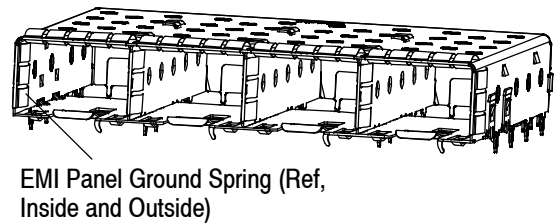
SFP Enhanced EMI Single Port Cage Assembly

Enhanced EMI Panel Ground Springs With Light Pipe



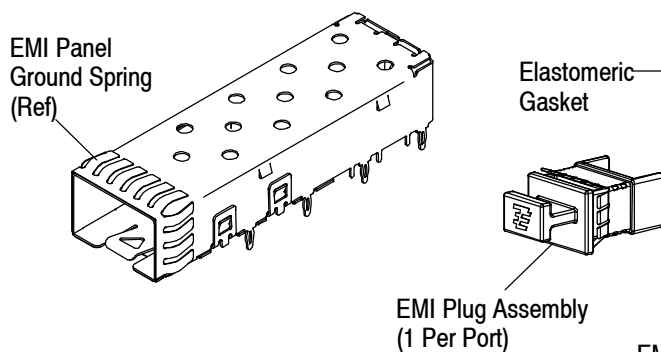
SFP Enhanced EMI Ganged Assembly

*1 × 4 Configuration
Enhanced EMI Panel Ground Springs Without Light Pipe*



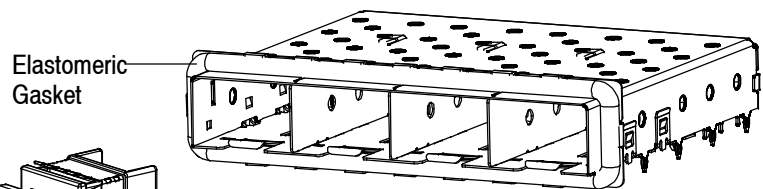
SFP+ Single Port Cage Assembly

External EMI Panel Ground Springs Without Light Pipe

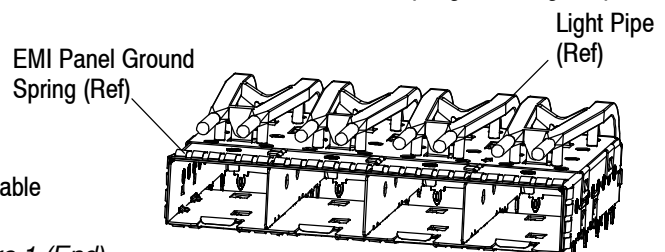


SFP+ Ganged Cage Assembly

1 × 4 Configuration Elastomeric Gasket Without Light Pipe



*1 × 4 Configuration
External EMI Panel Ground Springs With Light Pipe*



Note: Different Compliant Pin Contact Configurations Are Available

Figure 1 (End)

Each connector is a housing with right-angle surface mount contacts. The connectors (with the exception of the 16G SFP+ connectors) features an embossed “1” for Pin 1 identification, a chamfered corner for orientation, alignment posts that provide stability for placement on the pc board, standoffs to allow easy pc board cleaning after soldering, and a card entry slot that accepts a 1.0±0.1 mm thick integrated circuit card housed in the transceiver module. The 16G SFP+ connector does not have an embossed “1” Pin 1 identification or chamfered corner orientation feature.

Each cage assembly is a frame with compliant pin contacts; available with or without electromagnetic interference (EMI) suppression pins. The cage assembly features thermal vent holes, a locking latch for holding the mating transceiver module in place, kick-out spring to release the transceiver module for removal, and panel grounding features (panel ground springs and elastomeric gasket) to provide electrical contact to the bezel. The dust cover (SFP cage assemblies) or the EMI plug assembly (SFP+ cage assemblies)—one for each port—is used when the transceiver module is not mated to the cage assembly to prevent contaminants from entering the chassis.

The SFP+ cage assembly is available in two versions: elastomeric gasket, and external EMI panel ground springs (springs are on the outside of the cage assembly). The elastomeric gasket cage assembly is available in ganged only. The external EMI panel ground springs cage assembly is available in single port and ganged (1 × 2, 1 × 4, and 1 × 6). Both versions are available with or without light pipes.

2. REFERENCE MATERIAL

2.1. Revision Summary

Revisions to this application specification include:

- Added 16 Gb/s SFP+ Connector throughout document and new artwork to Figures 1, 13, and 14
- Added or changed text in Section 1, INTRODUCTION; Paragraph 2.2 and 2.4

2.2. Customer Assistance

Reference product base part numbers 1367073 and 1489669 and product code A438 are representative of SFP surface mount PT connectors and cage assemblies; reference product base part number 2110759 and product code L759 are representative of 16 Gb/s SFP+ surface mount PT connectors; and reference product base part numbers 1888247 and 2007135 and product code K638 are representative of SFP+ surface mount PT connectors and cage assemblies. Use of these numbers will identify the product line and expedite your inquiries through a service network established to help you obtain product and tooling information. Such information can be obtained through a local Representative or, after purchase, by calling PRODUCT INFORMATION at the number at the bottom of page 1.

2.3. Drawings

Customer drawings for product part numbers are available from the service network. If there is a conflict between the information contained in the customer drawings and this specification or with any other technical documentation supplied, the information contained in the customer drawings takes priority.

2.4. Specifications

Product Specifications 108-1949 (SFP connector), 108-2424 (SFP 16Gb/s Fiber Channel PT connector), and 108-1950 (SFP cage assemblies) provides product performance and test information.

2.5. Instructional Material

Instruction Sheets (408-series) provide product assembly instructions or tooling setup and operation procedures. Documents available which pertain to this product are:

- 408-8848 SFP PT Connector and Cage Assembly Seating Tool Kit
- 408-8849 SFP Cage Assembly Extraction Tool
- 408-10300 SFP+ Cage Assembly Removal Tool Assemblies 1976584-1, 1976597-1, and 1976920-1

3. REQUIREMENTS

3.1. Safety

Do not stack component packages so high that the shipping containers buckle or deform.

3.2. Limitations

A. Connector

The connector is designed to operate in a temperature range of -55° to 85°C [-67° to 185°F].

B. Transceiver Module

For applications using ganged cage assemblies, the width of the mating transceiver module (portion outside of the cage assembly) cannot exceed the width of the port of the cage assembly. This will prevent any possible interference between ports when inserting the transceiver modules. Port-to-port centerline spacing is 14.25 mm; therefore, the maximum width of the transceiver (outside of the cage assembly) cannot exceed 14 mm.

3.3. Material

The connector housing is made of liquid crystal polymer (LCP) thermoplastic, UL 94-V-0. The surface mount contacts are made of phosphor bronze plated with gold over nickel. The cage assemblies are made of copper alloy. The dust cover is made of thermoplastic, and the EMI plug assembly is made of zinc die cast with a copper alloy spring.

3.4. Storage

A. Ultraviolet Light

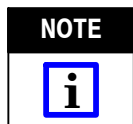
Prolonged exposure to ultraviolet light may deteriorate the chemical composition used in the connector material.

B. Shelf Life

The connector and cage assembly should remain in the shipping containers until ready for use to prevent deformation to any protruding parts. The connectors and cage assemblies should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance.

C. Reeled Components

The connectors are supplied in reels on carrier tapes approved under Electronic Industries Alliance (EIA)-481. These reels have a maximum diameter of 360 with 480 connectors per reel. Store coil wound reels horizontally and traverse wound reels vertically.



Refer to Section 5 for carrier tape dimensions.

3.5. Chemical Exposure

Do not store connectors or cage assemblies near any chemical listed below as they may cause stress corrosion cracking in the contacts.

| | | | | | |
|----------|------------|----------|------------|----------|------------------|
| Alkalies | Ammonia | Citrates | Phosphates | Citrates | Sulfur Compounds |
| Amines | Carbonates | Nitrites | Sulfur | Nitrites | Tartrates |

3.6. PC Board

A. Material and Thickness

The pc board material shall be glass epoxy (FR-4 or G-10). The minimum pc board thickness must be 1.5 mm for mounting the connector and cage assembly to one side of the board. For mounting to both sides of the board, the minimum pc board thickness must be 3.0 mm for single port cage assemblies and 2.25 mm for SFP ganged, SFP enhanced EMI ganged, and SFP+ external EMI panel ground spring cage assemblies.

B. Tolerance

Maximum allowable bow of the pc board shall be 0.08 mm over the length of the cage assembly. The coplanarity of the pc board circuit pads must be 0.03 mm.

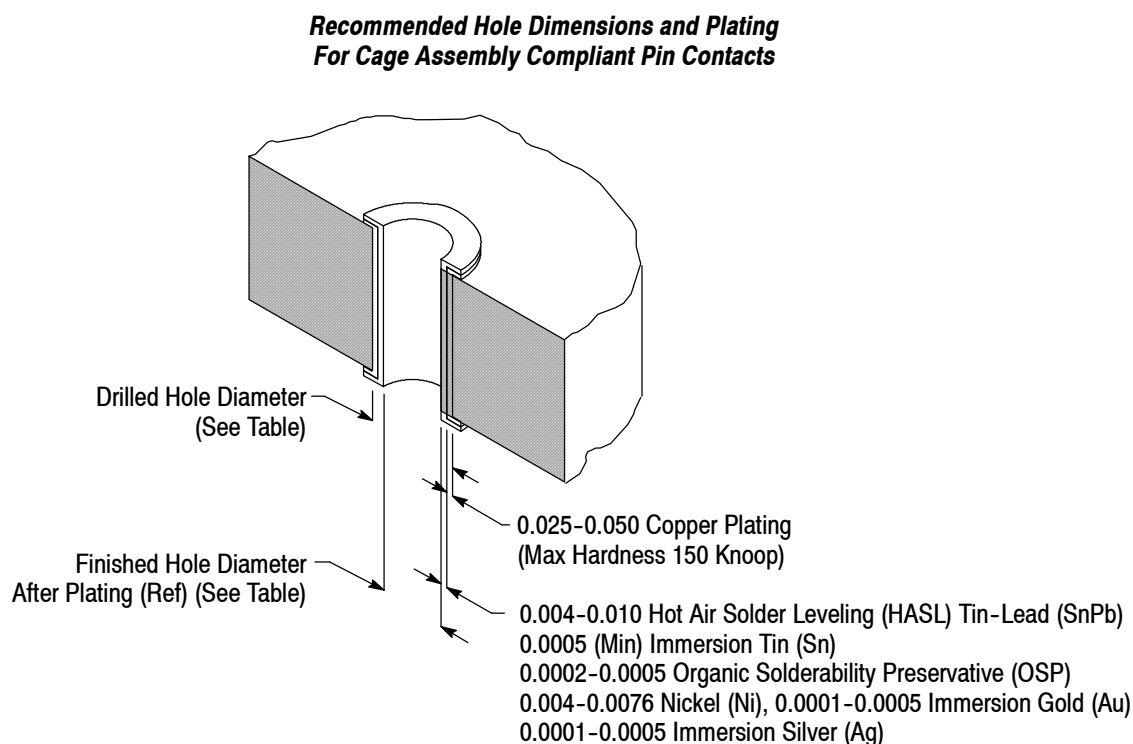
C. Pads

The pads must be solderable in accordance with EIA-364-52.

D. Hole Dimension

The holes for the cage assembly compliant pin contacts must be drilled and plated through. Recommended drilled hole diameter and plating type and thickness, and reference finished hole size are provided in Figure 2.

Holes for the EMI suppression pins must be drilled and can be used with or without plating. The finished hole diameter is provided on the customer drawing for the specific cage assembly. The finished hole diameter for connector alignment posts are provided on the customer drawing for the specific connector.



| HOLE (See Customer Drawing for Hole Designation; Also Shown in Figure 3—Sample PC Board Layout) | DIAMETER | |
|---|--------------|----------------------------------|
| | DRILLED HOLE | FINISHED HOLE (After Plating) |
| A | 1.15±0.02 | 1.05 (Ref) |
| B | 1.05±0.02 | 0.95 (Ref) |
| C | 0.95±0.02 | 0.85 (Ref) |

Figure 2

E. Layout

The pc board holes and circuit pads must be precisely located to ensure proper placement and optimum performance of the connector and cage assembly. The layout must be designed using the dimensions provided on the customer drawing for the specific connector and cage assembly. A *sample* layout is provided in Figure 3.

When mounting cage assemblies to both sides of the board, the same EMI suppression pin holes must be shared by the cage assemblies on the opposite side of the board.

**Sample Recommended PC Board Layout
(Connector and Single Port Cage Assembly)**

Note: For a Specific PC Board Layout, Refer to the Customer Drawing for the Specific Connector and Cage Assembly

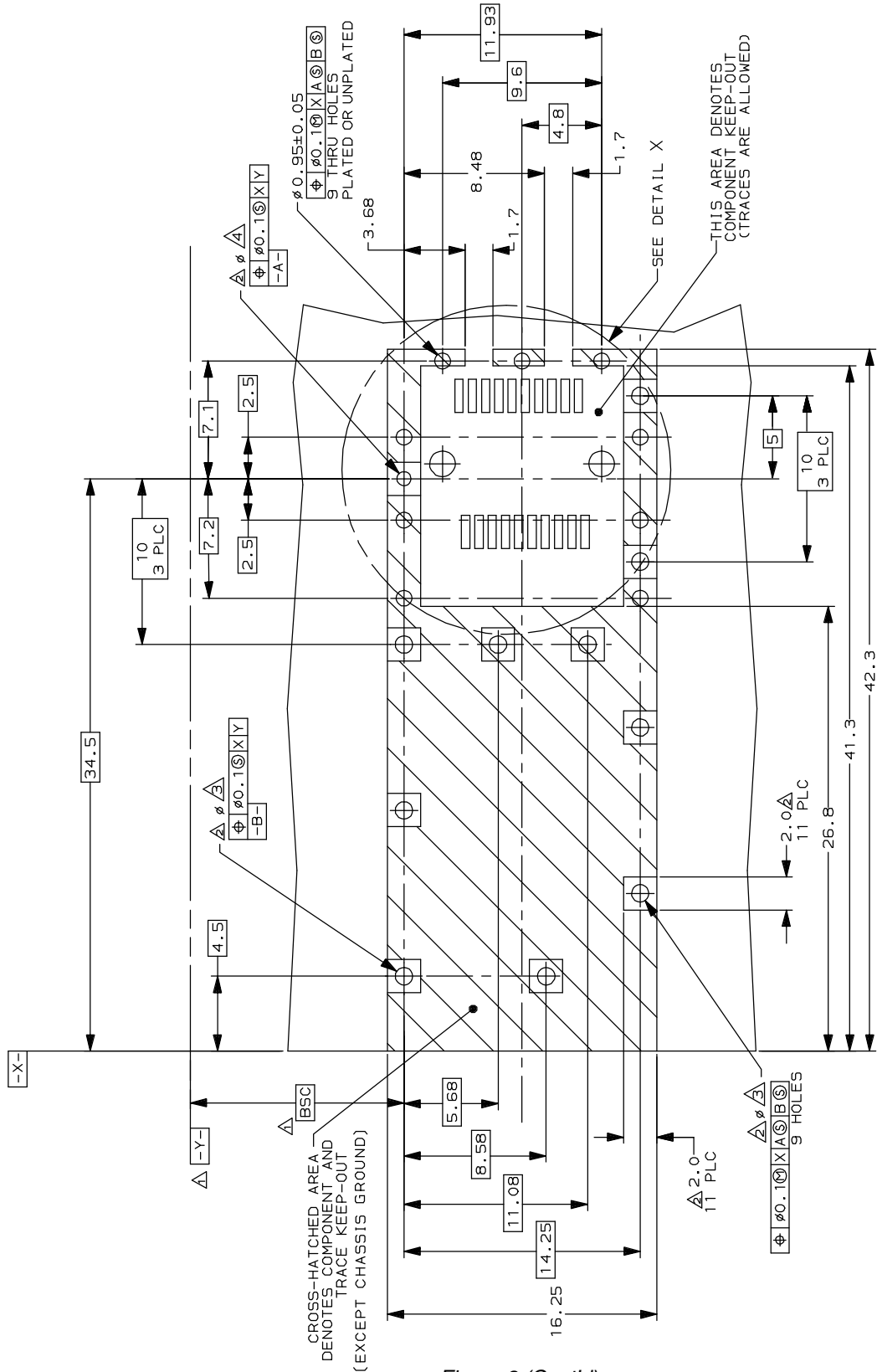


Figure 3 (Cont'd)

- ▲ Datum and Basic Dimension Established by Customer
- ▲ Pads and Vias and Chassis Ground, 11 Places
- ▲ Refer to Figure 2, Hole A
- ▲ Refer to Figure 2, Hole C

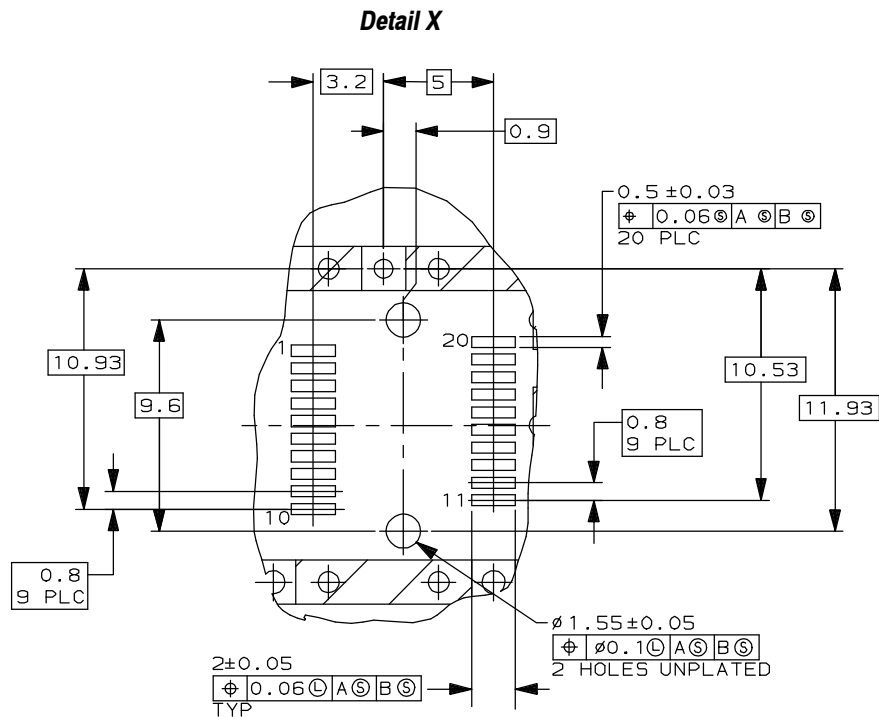


Figure 3 (End)

3.7. Solder Paste Characteristics

1. Alloy type for tin-lead solder shall be 63 Sn/37 Pb, 60 Sn/40 Pb, or 62 Sn/36 Pb/2 Ag.
Alloy type for lead-free solder shall be compatible with pure tin or gold; for example, SAC305 (96.5 Sn/3 Ag/0.5 Cu) or SAC405 (95.5 Sn/4 Ag/0.5 Cu).
2. Flux incorporated in the paste shall be rosin, mildly active (RMA) type.
3. Paste will be at least 80% solids by volume.
4. Mesh designation -200 to +325 (74 to 44 square micron openings, respectively).
5. Minimum viscosity of screen print shall be $5 \times 10\%$ cp (centipoise).
6. Minimum viscosity of stencil print shall be $7.5 \times 10\%$ cp (centipoise).

3.8. Solder Volume

Minimum solder volume (V) (before curing) for each circuit pad is calculated by multiplying the pad length (L) by the pad width (W) by the stencil thickness (T):

$$2.0(L) \times 0.5(W) \times 0.15(T) = 0.15 \text{ mm}^3 (V)$$

Solder volume for each connector must be 0.15 mm^3 per contact solder tine.

NOTE

Solder volume may vary depending on solder paste composition.



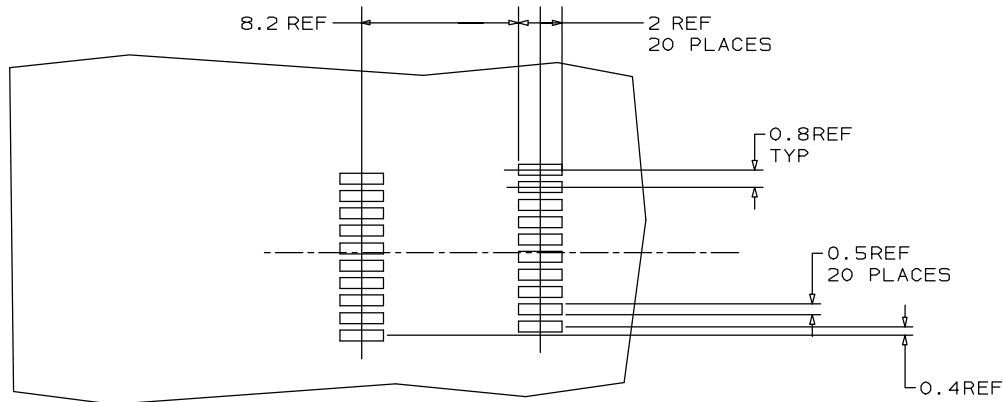
3.9. Solder Paste Thickness

Solder paste thickness for the connector contact solder tines must be at least 0.15 mm.

3.10. Stencil

The stencil aperture is determined by the circuit pad size and stencil thickness. It may be any shape as long as it prevents solder bridging from one pad to another. Generally, a thinner stencil will need a larger aperture to maintain the given volume of solder paste. The stencil should be 0.15 mm thick. The stencil layout must be designed using the dimensions provided on the customer drawing for the specific connector. Sample stencil layout is provided in Figure 4.

Sample Recommended Connector Stencil Layout



Note: For Specific Circuit Pad Locations, Refer to the Customer Drawing for the Specific Connector

Figure 4

3.11. Solder Mask

When soldering, solder mask is recommended between all circuit pads to minimize solder bridging between pads. The mask must not exceed the height of the pad. If a trace is run between adjacent pads on the pc board, a solder mask must be applied over the trace to prevent bridging and wicking of solder away from the connector contact solder tines. Mask most suitable is Liquid Photo Imageable.

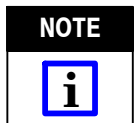


All traces must be covered by solder mask in the solder deposit area. Exposed traces could cause bridging and create a short, or wick solder away from the solder tines, producing a weak solder joint.

3.12. Connector Placement



Connectors should be handled only by the housing to avoid deformation, contamination, or damage to the contact solder tines.



The connector must be soldered to the pc board BEFORE seating the cage assembly.

A. Registration

The connector contact solder tines must be aligned with matching circuit pads and alignment posts aligned with matching holes before placing the connector onto the pc board.

B. Position

Optimally, the connector contact solder tines should be centered on the pc board circuit pads. However, slight misalignment is permissible as shown in Figure 5.

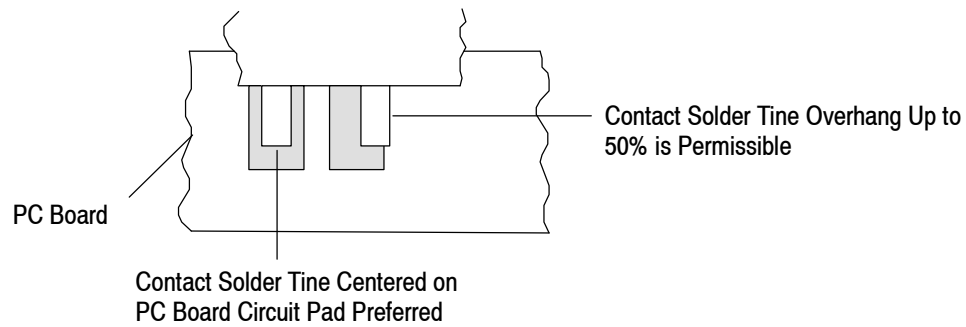


Figure 5

C. Seating

Because the connector alignment posts are for clearance and fit only, the force required to seat the connector is minimal. Apply only that force necessary to seat the contact solder tines into the top surface of the solder paste. The alignment posts must be inserted into the pc board holes and the standoffs must be seated on the board. See Figure 6.

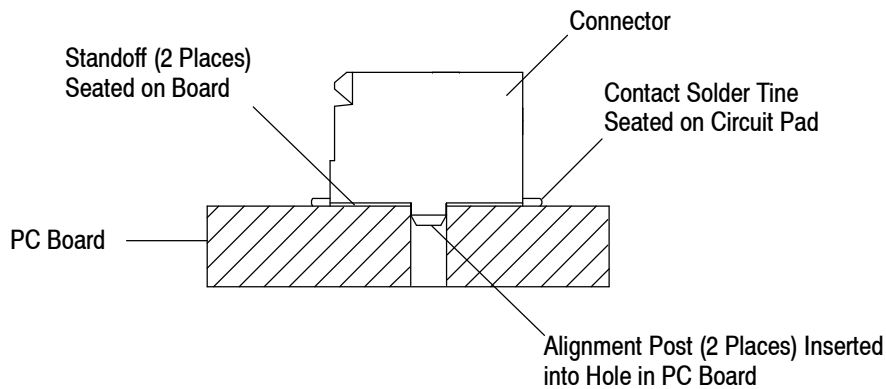


Figure 6

3.13. Soldering

A. Process

The connector must be soldered using non-focused infrared (IR) reflow or equivalent soldering technique. When mounting to both sides of the pc board, the surface tension of the solder, when it is in the liquid state, will hold the connector on the board.

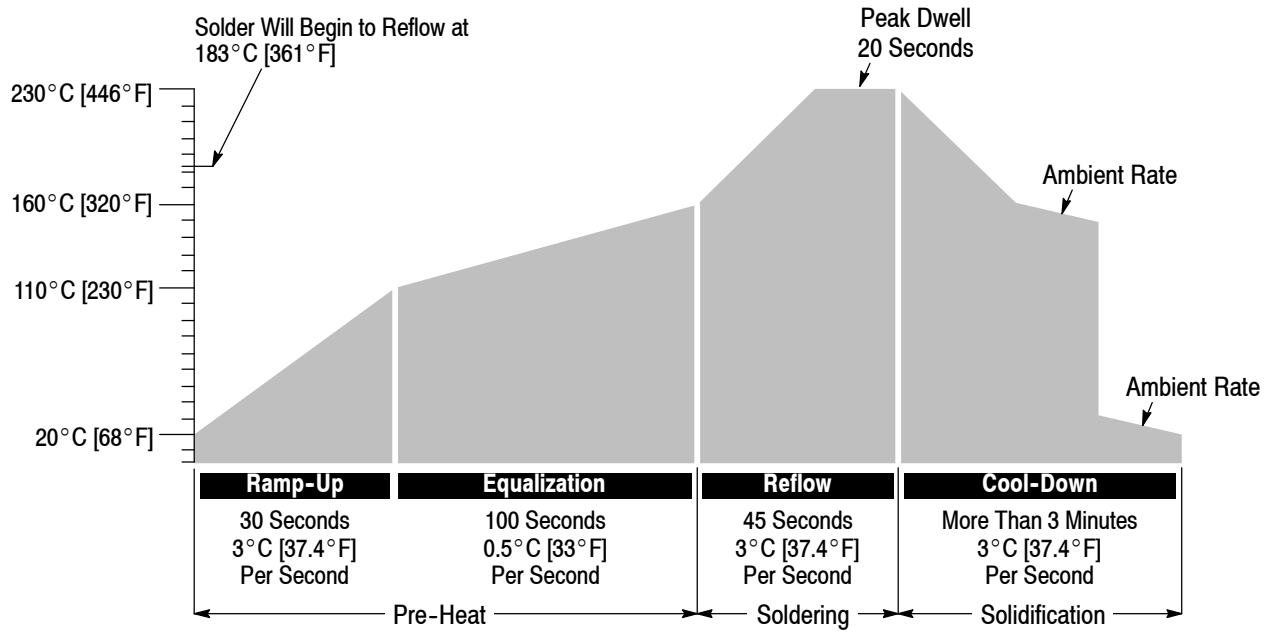
Reflow temperature and time may vary depending on the size of the pc board and placement of other components. The reflow temperature and approximate time to which the connector can be subjected is specified in Figure 7.



Excessive temperatures may cause connector housing degradation. It is recommended that component temperatures not exceed 230°C [446°F] when using tin-lead solder and 260°C [500°F] when using lead-free solder.

Reflow Soldering Process Cycle

Tin-Lead Solder
(Maximum 230°C [446°F] for 20 Seconds)



Lead-Free Solder
(Maximum 260°C [500°F])

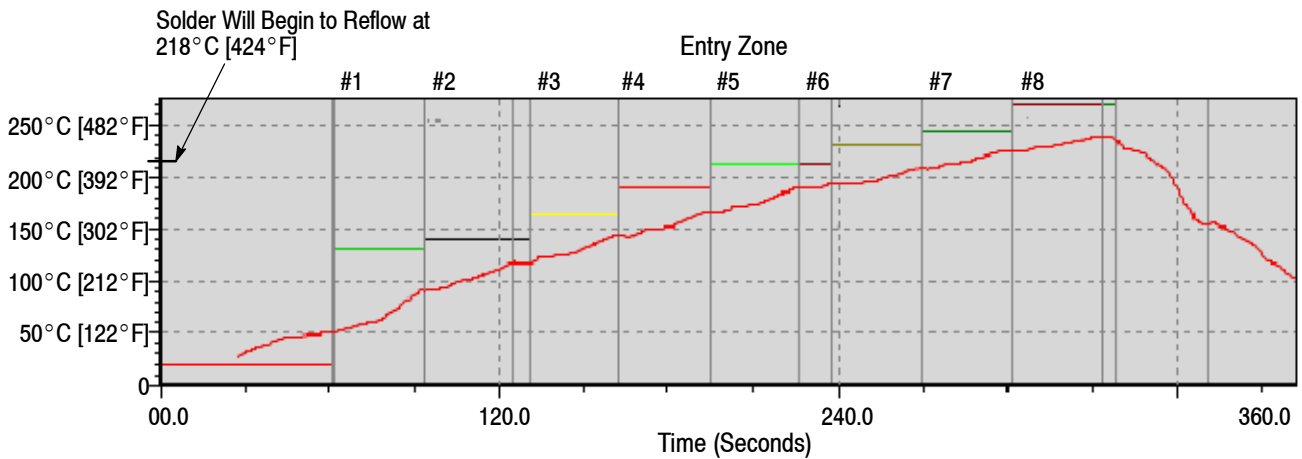


Figure 7

B. Cleaning

After soldering, removal of fluxes, residues, and activators is necessary. Consult with the supplier of the solder and flux for recommended cleaning solvents. Cleaners must be free of dissolved flux and other contaminants. It is recommended cleaning the pc board on its edge. If using aqueous cleaner, standard equipment such as a soak-tank or an automatic in-line machine should be used. Common cleaning solvents that will not affect the connector for the time and temperature specified are listed in Figure 8.



Consideration must be given to toxicity and other safety requirements recommended by the solvent manufacturer. Refer to the manufacturer's Material Safety Data Sheet (MSDS) for characteristics and handling of cleaners. Trichloroethylene and Methylene Chloride is not recommended because of harmful occupational and environmental effects. Both are carcinogenic (cancer-causing).

| CLEANER | | TIME (Minutes) | TEMPERATURE (Maximum) |
|-------------------|---------|-------------------|--------------------------|
| NAME | TYPE | | |
| ALPHA 2110 | Aqueous | 1 | 132°C [270°F] |
| Isopropyl Alcohol | Solvent | 5 | 100°C [212°F] |
| KESTER 5778 | Aqueous | 5 | 100°C [212°F] |
| KESTER 5779 | Aqueous | 5 | 100°C [212°F] |
| LONCOTERGE 520 | Aqueous | 5 | 100°C [212°F] |
| LONCOTERGE 530 | Aqueous | 5 | 100°C [212°F] |

Figure 8

C. Drying

When drying cleaned assemblies and pc boards, make certain that temperatures do not exceed 85°C [185°F]. Excessive temperatures may cause connector housing degradation.

3.14. Checking Installed Connector

All solder joints must conform to those specified in Workmanship Specification 101-21 and all other requirements specified in this document. The installed connector must have solder fillets evenly formed around each contact solder tine. Solder must have 95% minimum coverage over the circuit pad. See Figure 9.

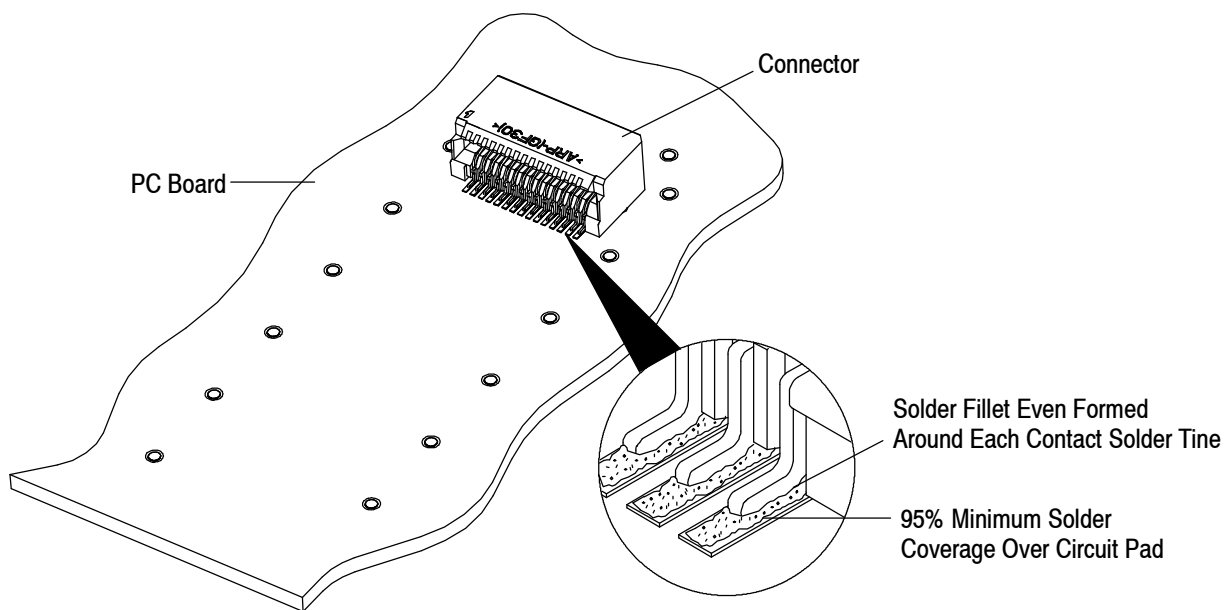


Figure 9

ALPHA, KESTER, and LONCOTERGE are trademarks of their respective owners.

3.15. Bezel

A. Thickness

The bezel thickness range shall be 0.8 mm through 2.6 mm.

B. Cutout

The bezel must provide a cutout that allows proper mounting of the cage assembly. The cage assembly panel grounding feature must be compressed by the bezel in order to provide an electrical ground between the cage assembly and bezel for EMI suppression. Care must be used to avoid interference between adjacent cage assemblies and other components. The minimum allowable distance between cage assemblies must be considered to ensure proper assembly. Dimensions for bezel cutout and minimum allowable distance between cutouts are shown in Figure 10.



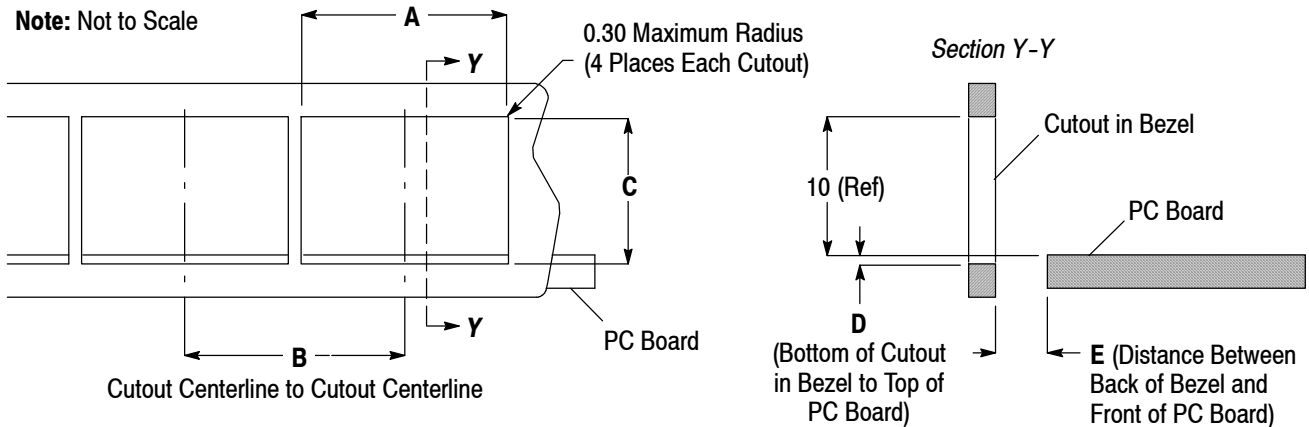
It is strongly recommended that the bezel configuration shown for non-peripheral component interconnect (PCI) application and the bezel configuration shown for PCI application be used only for the cage assemblies indicated. Requirements for non-PCI applications were intended to be used in the communications industry only.

3.16. PC Board and Bezel Position

The bezel and pc board must be positioned in relation to each other to avoid interference with the function of the cage assembly module locking latch and to ensure proper function of the panel grounding feature. This relationship must conform to the dimensions given in Figure 10.

**Recommended Bezel Cutout (Minimum Pitch) and
PC Board and Bezel Position
For Cage Assemblies Without Light Pipe**

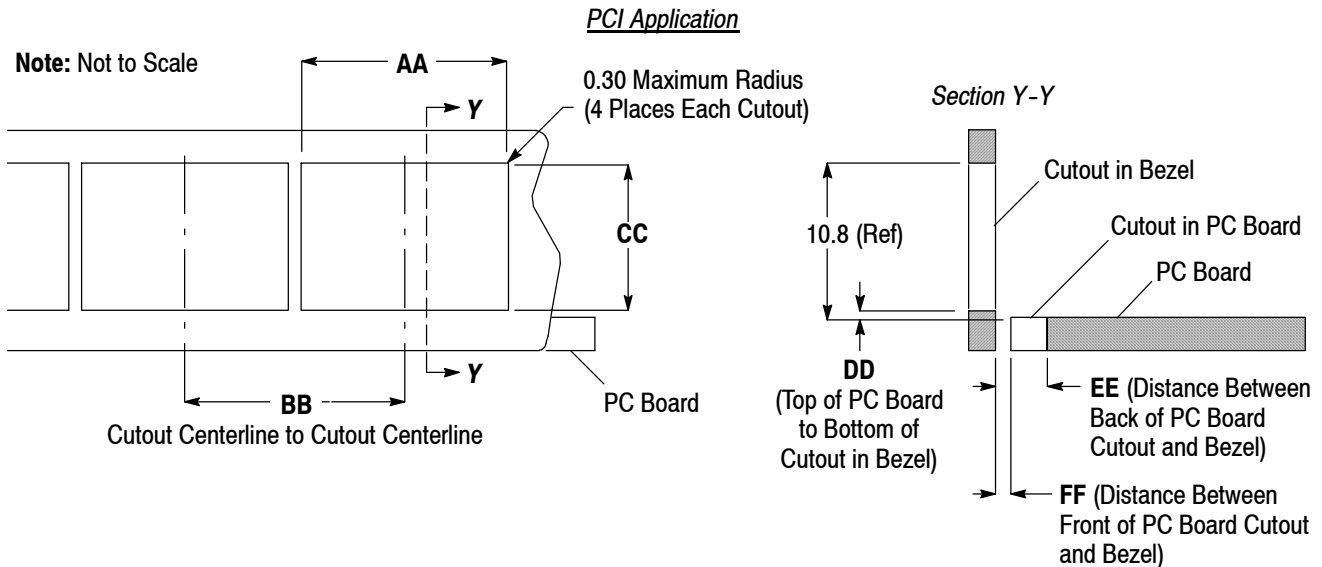
Non-PCI Application



| CAGE ASSEMBLY CONFIGURATION | DIMENSION (Non-PCI Application) | | | | | | | | | |
|-----------------------------|---------------------------------|---------|-------------|-------------|---------------|-------------------------|---------|-------------|-------------|---------------|
| | SFP CAGE ASSEMBLY | | | | | SFP+ CAGE ASSEMBLY | | | | |
| | | | | | | With Elastomeric Gasket | | | | |
| | A ± 0.1 | B (Min) | C ± 0.1 | D ± 0.1 | E | A ± 0.1 | B (Min) | C ± 0.1 | D ± 0.1 | E |
| Single Port | 15.25 | 16.25 | 10.40 | 0.40 | 2.9 ± 0.9 | NA | NA | NA | NA | NA |
| 1 \times 2 Ganged | 29.50 | 30.75 | 10.15 | 0.15 | 2.9 ± 0.9 | 29.70 | 34.10 | 10.4 | 0.23 | 3.5 ± 0.3 |
| 1 \times 4 Ganged | 58.00 | 59.25 | 10.15 | 0.15 | 2.9 ± 0.9 | 58.20 | 62.60 | 10.4 | 0.23 | 3.5 ± 0.3 |
| 1 \times 6 Ganged | 86.50 | 87.75 | 10.15 | 0.15 | 2.9 ± 0.9 | 86.70 | 91.10 | 10.4 | 0.23 | 3.5 ± 0.3 |

Figure 10 (Cont'd)

| CAGE ASSEMBLY CONFIGURATION | DIMENSION (Non-PCI Application) | | | | |
|-----------------------------|---|---------|-------------|-------------|---------------|
| | SFP+ CAGE ASSEMBLY With External EMI Panel Ground Springs | | | | |
| | A ± 0.1 | B (Min) | C ± 0.1 | D ± 0.1 | E |
| Single Port | 15.25 | 16.25 | 10.4 | 0.23 | 3.5 ± 0.3 |
| 1 \times 2 Ganged | 29.70 | 30.75 | 10.4 | 0.23 | 3.5 ± 0.3 |
| 1 \times 4 Ganged | 58.20 | 59.25 | 10.4 | 0.23 | 3.5 ± 0.3 |
| 1 \times 6 Ganged | 86.70 | 87.75 | 10.4 | 0.23 | 3.5 ± 0.3 |



| CAGE ASSEMBLY CONFIGURATION | DIMENSION (PCI Application) | | | | | |
|-----------------------------|-----------------------------|----------|--------------|--------------|---------------|----------------|
| | SFP and SFP+ CAGE ASSEMBLY | | | | | |
| | AA ± 0.1 | BB (Min) | CC ± 0.1 | DD ± 0.1 | EE | FF |
| Single Port | 15.25 | 16.25 | 10.40 | 0.40 | 3.5 ± 0.3 | 1.02 ± 0.3 |
| 1x6 Ganged | 86.5 | 87.75 | 10.15 | 0.65 | 3.5 ± 0.3 | 1.02 ± 0.3 |

Figure 10 (End)

3.17. Cage Assembly Placement

NOTE

The connector must be soldered to the pc board BEFORE seating the cage assembly.



A. Registration

The compliant pin contacts and EMI suppression pins must be aligned with matching holes in the pc board, then inserted into the pc board simultaneously to prevent twisting or bending of these parts.

B. Seating

Using proper seating force and seating height is essential to interconnection performance. The force used to seat the cage assembly must be applied evenly to prevent deformation or other damage to the compliant pin contacts. The force required to seat the cage assembly onto the pc board can be calculated by:

$$\text{Amount of Compliant Pin Contacts} \times 44.5 \text{ N [10 lbs]} \text{ (Force per Compliant Pin Contact)} = \text{Seating Force}$$

CAUTION


Over-driving of the cage assembly will deform parts critical to the quality of the connection. Maximum force occurs prior to the cage assembly bottoming on the pc board.

When using tooling to seat a ganged cage assembly, the *shut height* of the application tool must be specifically set for proper seating of the cage assembly. The shut height can be calculated by:

$$\text{Seating Height (Cage Assembly Seated)} + \text{Height of Seating Tool} + \text{Combined Thicknesses of PC Board and PC Board Support Fixture} = \text{Shut Height (Ram Down)}$$



The shut height may need to be adjusted to maintain the 0.10 mm maximum gap between the standoffs of the cage assembly and the pc board.

The cage assembly must be seated on the pc board not exceeding the dimensions shown in Figure 11.

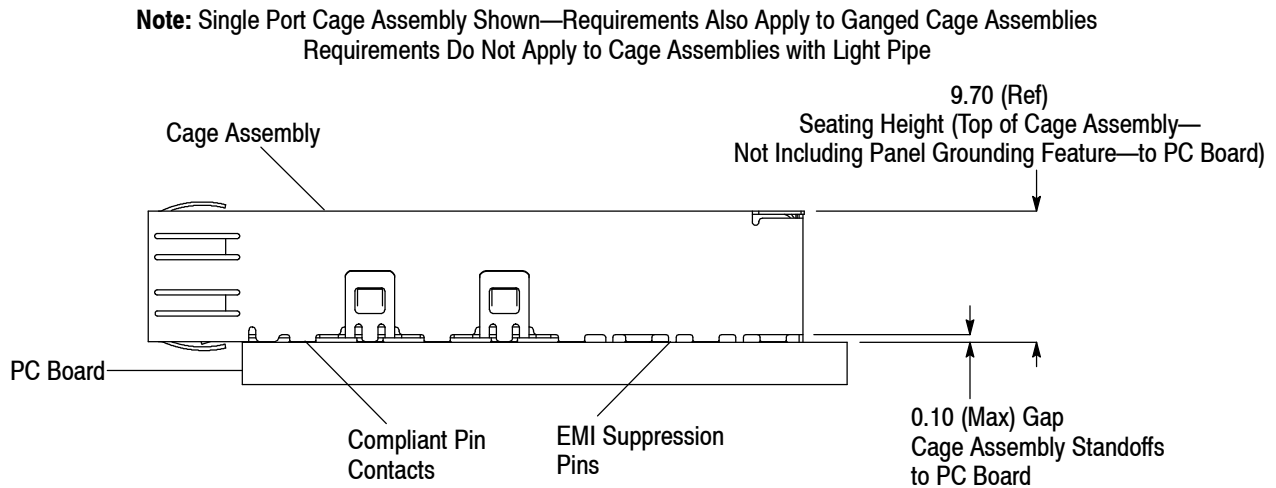


Figure 11

3.18. Checking Installed Cage Assembly

After installation, the cage assembly panel grounding feature must be compressed by the bezel. A slight bow in the cage assembly is permitted. The bezel must not interfere with the function of the module locking latch. The bezel and pc board must be positioned according to the dimensions shown in Figure 12.

3.19. Port Protection

A dust cover (for SFP cage assembly) or EMI plug assembly (for SFP+ cage assembly) must be installed into the port when the transceiver module is not mated with the cage assembly.

3.20. Removal and Repair

The cage assembly must be removed from the pc board before removing the connector. Standard de-soldering methods must be used to remove the connector from the pc board. The connector and cage assembly **MUST NOT** be re-used after removal.

For removal of the single port cage assembly, a flat metal bar (or similar object) can be partially inserted into the port of the cage assembly (the object **MUST NOT** touch the connector; otherwise, damage to the surface mount contacts could occur), then the cage assembly can be removed by lifting it off of the pc board.

For removal of a ganged cage assembly, an extraction tool must be used (refer to Section 5).

The connector and cage assembly are not repairable. Any defective or damaged products **MUST NOT** be used.

4. QUALIFICATION

SFP and SFP+ surface mount PT connectors are Recognized by Underwriters Laboratories Inc. (UL) in File E28476.

Note: Single Port Cage Assembly Shown—Requirements Also Apply to Ganged Cage Assemblies Without Light Pipe
Requirements Do Not Apply to Cage Assemblies with Light Pipe

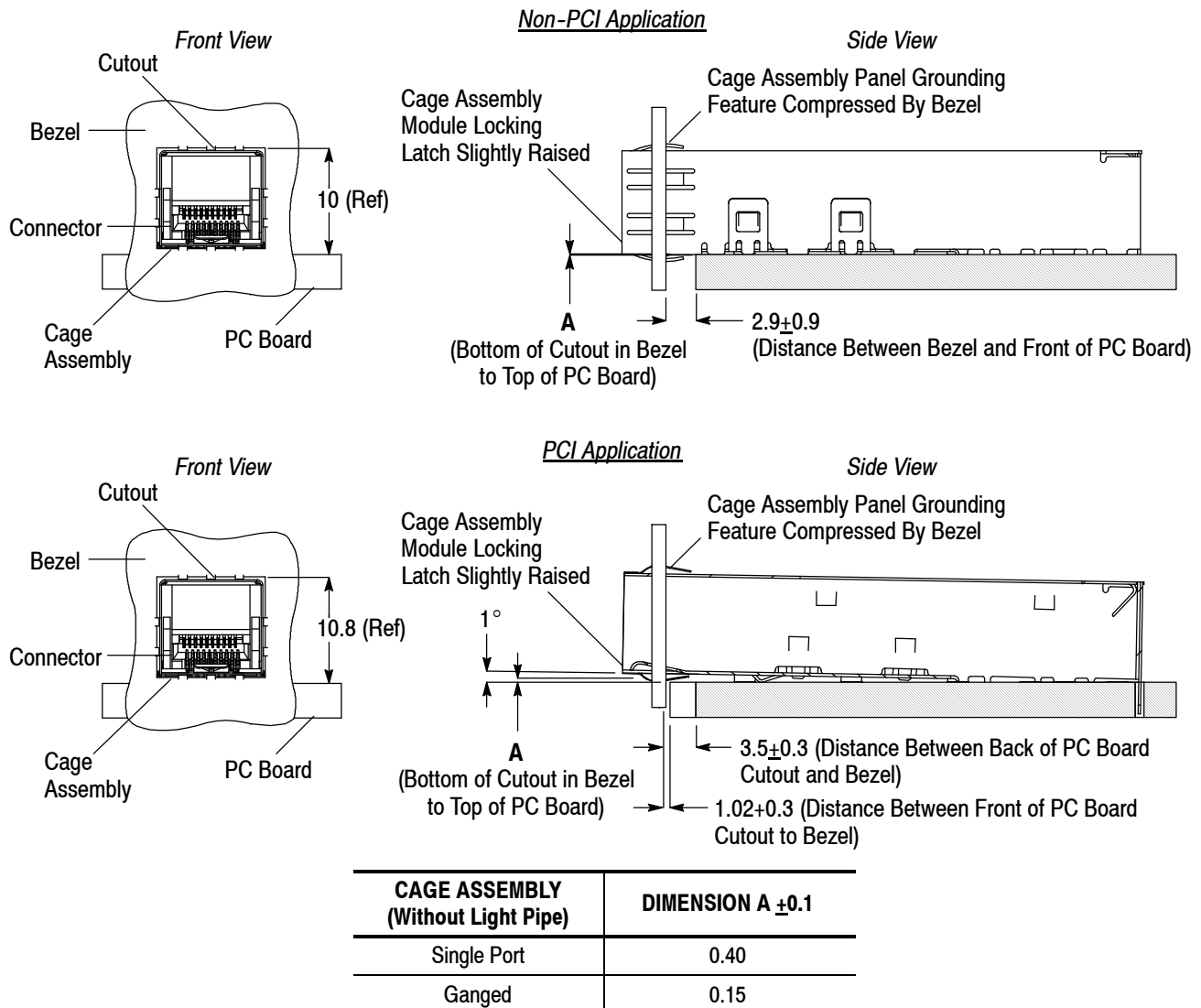


Figure 12

5. TOOLING

No tooling is required for manual placement of the connector onto the pc board. For placement of the single port cage assembly onto the pc board, flat rock tooling can be used; extreme caution must be taken not to touch or damage the panel grounding feature during seating. Tooling is available for seating and removing a ganged cage assembly.

For automatic machine placement of the connector, the robotic equipment must have a true position accuracy tolerance sufficient to properly locate the connector. This includes gripper and fixture tolerances as well as equipment repeatability. It must use the connector datum surfaces to ensure reliable placement.

Tooling part numbers and instructional material packaged with the tooling are given in Figure 13.

5.1. Seating Tool Kit

The seating tool kit (consists of a seating tool and wall support) is used to seat a ganged cage assembly onto the pc board. The seating tool and wall support are also available separately.

5.2. Extraction Tool

The cage assembly extraction tool is used to remove a ganged cage assembly from the pc board by pushing the compliant pin contacts and EMI suppression pins out of their holes without overstressing the contacts.

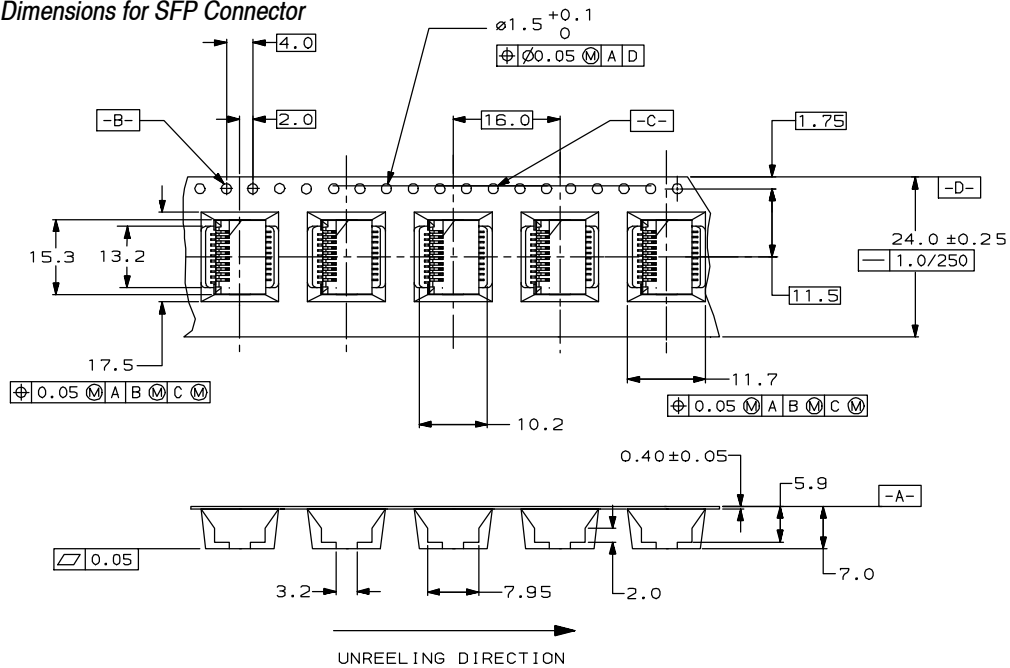
5.3. Application Tool

Power for the seating tools and extraction tools must be provided by application tool (with a ram) capable of supplying a downward force of 44.5 N [10 lb] per compliant pin contact. For available application tools, call PRODUCT INFORMATION at the number at the bottom of page 1.

5.4. PC Board Support Fixture

A pc board support must be used with the seating tool and extraction tool. The support fixture provides proper support for the pc board and protects the pc board and cage assembly from damage. When using the seating tool or extraction tool, the support fixture must be customer designed according to the instructions included with the tool being used.

Feed Strip Carrier Dimensions for SFP Connector



Feed Strip Carrier Dimensions for SFP+ 16Gb/s Connector

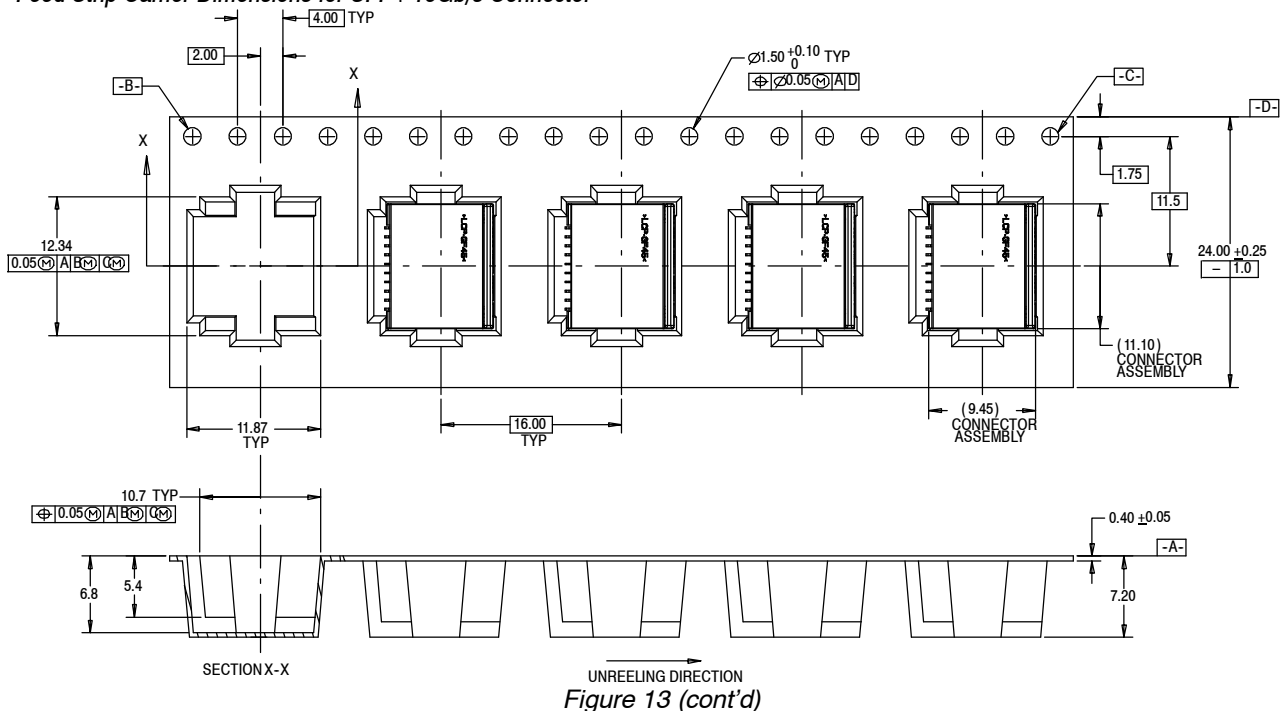
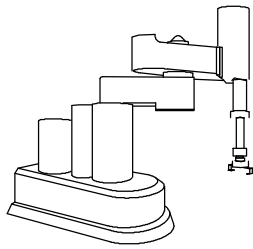
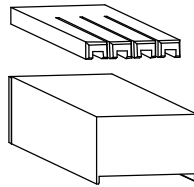


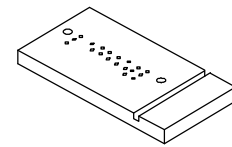
Figure 13 (cont'd)



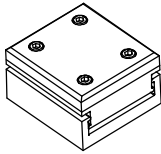
Robotic Equipment
(Designed Upon Request)



SFP PT Connector and Cage Assembly
Seating Tool Kits 1725609-[]
(408-8848)

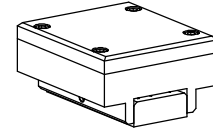


PC Board Support Fixture
(Application Specific,
Customer Supplied)



SFP+ Cage Assembly Removal Tool
Assemblies (See Table)
(408-10300)

SFP+ PT Connector and Cage Assembly
Seating Tool Kits 2018002-[]
(No Document Available)



SFP Cage Assembly Extraction Tools
(See Table)
(408-8849)

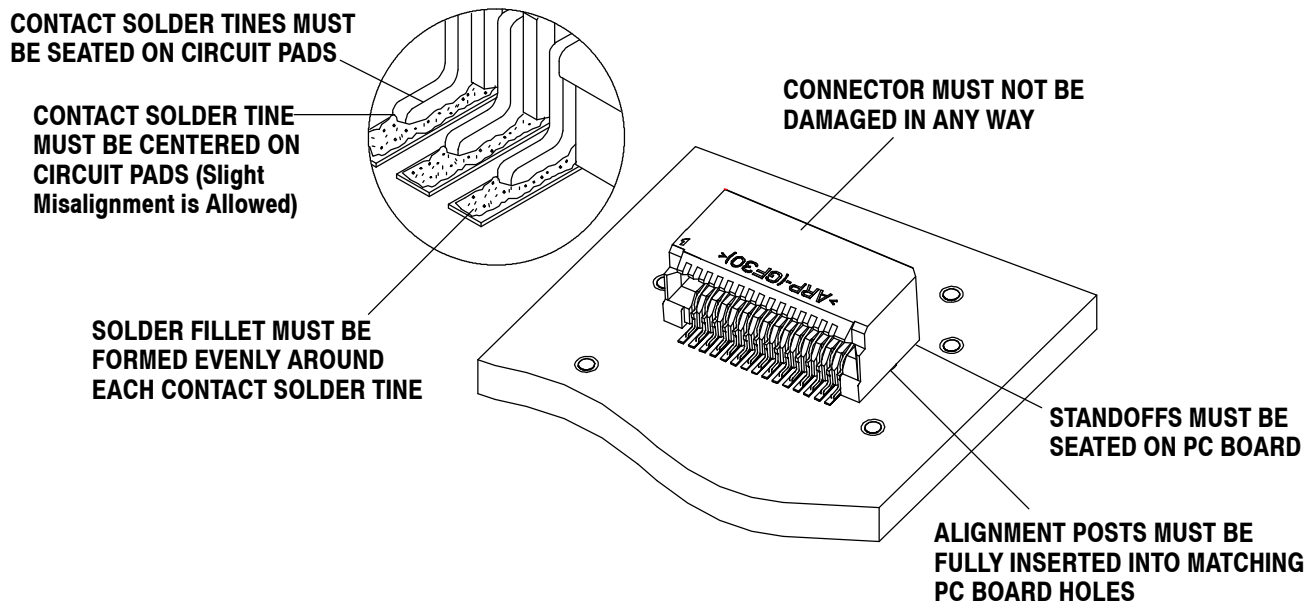
| CAGE ASSEMBLY | | SEATING TOOL KIT● | EXTRACTION OR REMOVAL TOOL |
|---------------|---------------|-------------------|----------------------------|
| Type | Configuration | | |
| SFP | 1 × 2 | 1725609-3 | 1213709-1 |
| | 1 × 4 | 1725609-1 | 1725612-1 |
| | 1 × 6 | 1725609-2 | 1213710-1 |
| SFP+ | 1 × 2 | 2018002-3 | 1976920-1 |
| | 1 × 4 | 2018002-1 | 1976584-1 |
| | 1 × 6 | 2018002-2 | 1976597-1 |

● The seating tool kit cannot be used to seat the connector or single port cage assembly.

Figure 13 (end)

6. VISUAL AID

Figure 14 shows a typical application of SFP and SFP+ surface mount PT connectors and cage assemblies. This illustration should be used by production personnel to ensure a correctly applied product. Applications which DO NOT appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.



**Note: Single Port Cage Assembly Shown
Requirements Also Apply to Ganged Cage Assembly
Requirements Do Not Apply to Cage Assembly with Light Pipe**

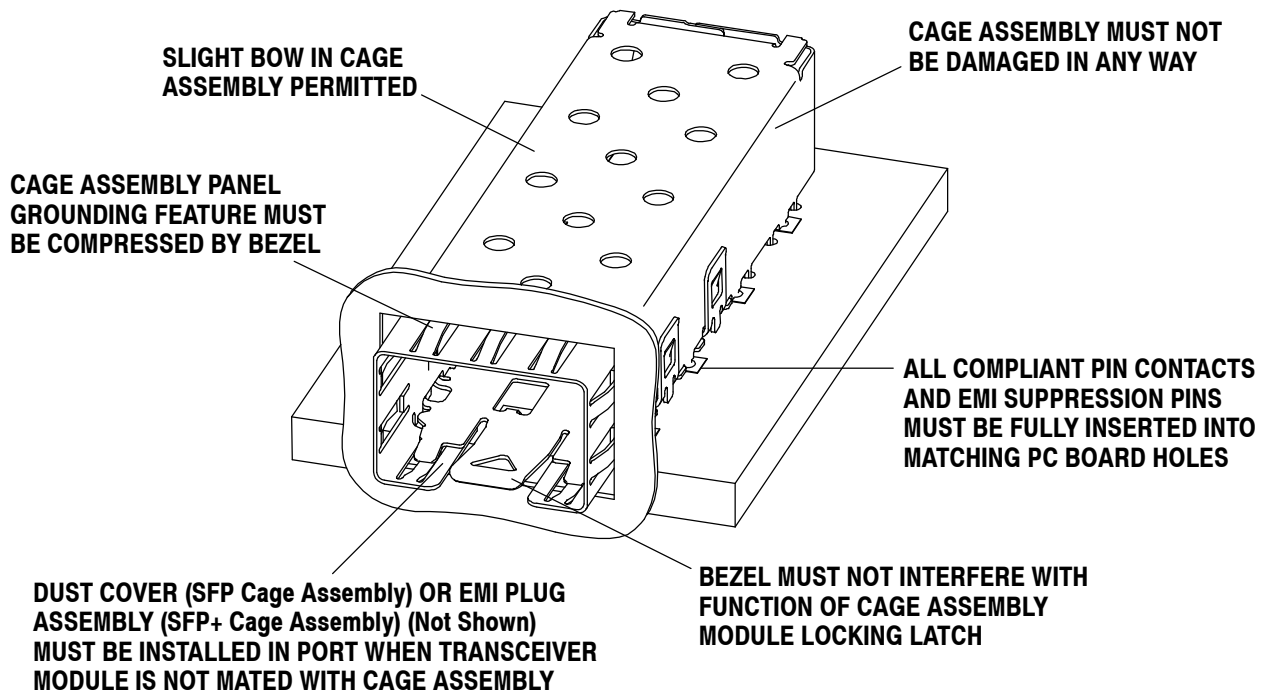


FIGURE 14 (CONT'D) VISUAL AID

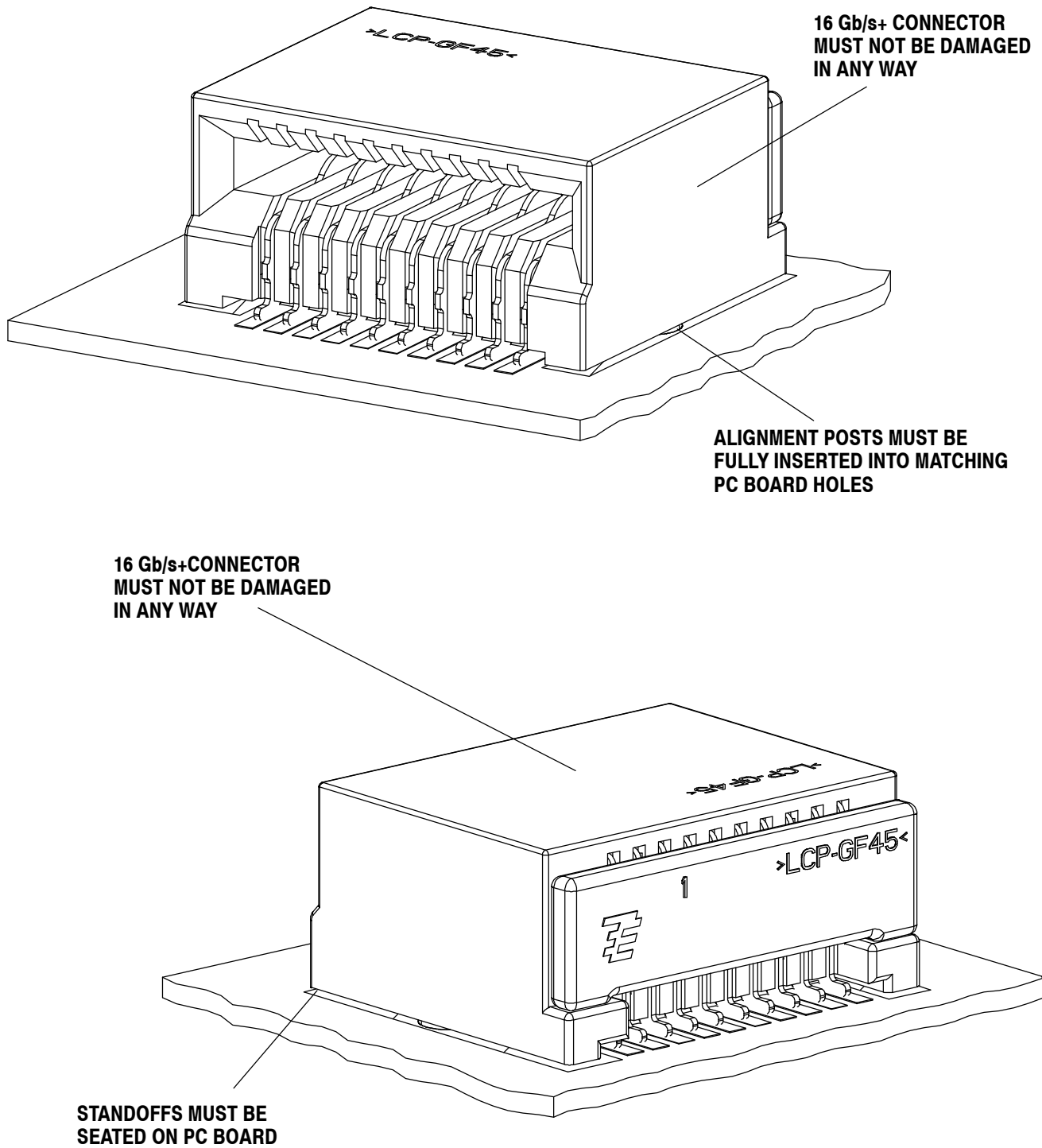


FIGURE 14 (END) VISUAL AID